ΙΠΤΑΠ5Υ5

Industrial 3D Printers High Performance Production Solutions



AMSY

INTAMISYS

About INTAMSYS

INTAMSYS is a world-leading high-tech company providing 3D printing and industrial direct additive manufacturing solutions for high-performance materials. It is co-founded by a team of engineers from world-class high-tech companies engaged in precision equipment development and high-performance materials research for many years.

Focusing on aerospace, aviation, automotive, electronic manufacturing, consumer goods, healthcare, scientific research and other industries, the company provides comprehensive additive manufacturing solutions from functional test prototyping, tooling and fixture manufacturing to direct mass production of final products, covering equipment, software, high-performance materials and printing services.

Collaboration with top filament manufacturers

Cooperating with top filament manufacturers

INTAMSYS cooperates with top filament manufacturers, through continuous testing and material comparison, finding out the most fitting materials for each applications. The wide range of materials includes PEEK, PEKK, ULTEM[™] (PEI), PPSU, PA, PA-CF, PC, ABS, and much more!

Defining the right process

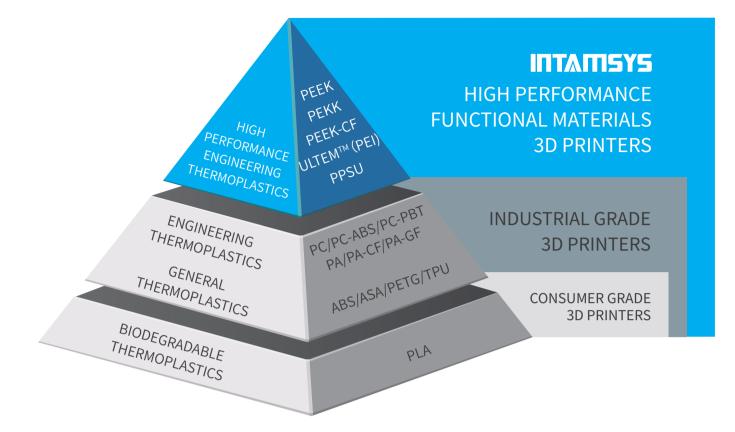
Customers can achieve the expected printing effect through preset printing parameters.

Meeting YOUR application requirements

INTAMSYS 3D printers now enable you to choose a wide range of polymers from many different manufacturers. Thanks to accurate printing parameters, the printing quality and experience has never been so good!



INTAMSYS High Performance 3D Printing Solutions



Customers



Filament Manufacturers



Applications







Healthcare





Global Sales & Support Networks





INTAMSYS is a world-leading high-tech company that provides high-performance 3D printing materials, direct additive manufacturing solutions and software.

Co-founded by a team of engineers with years of precision equipment development and high-performance material research, the company is headquartered in Shanghai. Currently, it has established a complete marketing and after-sales service system covering the whole world, with 2 European and American marketing and technical service centers, respectively located in Germany and in the United States.

INTAMSYS focuses on aerospace, automotive, electronic manufacturing, consumer products, medical, scientific research and other industries, providing complete additive manufacturing solutions, from functional test prototyping, tooling fixture manufacturing to customized mass production.



FUNMAT PRO 610HT

High Performance Materials Production Level 3D Printer

🛃 High Build Volume

High Build Volume Up to 610×508×508mm for Industrial Applications

High Performance Materials Production Capability

Able to Print Big Size PEEK/PEKK/ULTEM™ (PEI)/PPSU and other Functional Materials without Warpage

🧕 Advanced Thermal Design

Heated Chamber Up to 300°C (572°F), Extruder Up to 500°C (932°F)



Technical Parameters

| Model | FUNMAT PRO 610HT |
|------------------------------|--|
| Printing Technology | Fused Filament Fabrication (FFF) |
| Machine Size | 1710×1390×2080mm (67.3×54.7×80.1in) |
| Build Volume | 610×508×508mm (24×20×20in) |
| Build Platform | Vacuum Absorption Platform |
| Leveling | Automatic Leveling |
| Layer Thickness | 0.1-0.5mm |
| Max Travel Speed | XY: Max. 400mm/s Z: Max. 50mm/s |
| Printing Nozzles | 2 Printing Nozzles Without Scratching |
| Extruder Temperature | Max. 500°C/932°F |
| Chamber Temperature | Max. 300°C/572°F |
| Filament Chamber Temperature | Max 50°C/122°F, with dry compressed air (external air compressor is required). |
| Input File Type | .Stl/.Obj/.X3d/.3mf |
| Filament Diameter | 1.75mm |
| Position Resolution | XY: 12.5μm Z: 1.25μm |
| Motor Drive | High Precision Servo System |
| Smart Monitor & Control | Auto-Cleaning Nozzles/Filament Jam Warning/Filament Absence Warning/Liquid Cooling System & Vacuum Absorption Platform/Over Heat Protection/Auto-Switch Materials |
| Safety Certification | FCC/CE |
| Connectivity | WiFi/Ethernet/USB |
| Supported Materials* | PEEK/PEEK-CF/PEEK-GF/PEKK/ULTEM™ (PEI)/PPSU/PC-HT/PC/PC Alloys/PA-HT/ |
| | PA/PA-CF/ASA/ABS/HIPS/Carbon Fiber-Filled/GlassFiber-Filled/ESD-Safe, etc. |
| | |

*results of part printing may vary depending on material and/or design and size of the printed part

FUNMAT PRO 410

Smart Industrial Level 3D Printer

Smarter Design

Smart Dual Nozzles 3D Printing Solution, Automatic Leveling, Jam Warning

Advanced Thermal Design

Heated Chamber & Sealed and Dehumidified Filament Box, Liquid Cooling System, 500°C (932°F) Nozzles Temperature

Industrial-Grade Configuration

Industrial Grade Components for High Precision and High Quality Printing



Technical Parameters

| ModelFUNMAT PRO 410Printing TechnologyFused Filament Fabrication (FFF)Machine Size728×684×1480mm (28.7×26.9×58.3in)Build Volume305×305×406mm (12×12×16in)Build PlatformPI Sheet Heating+Ceramic GlassLevelingAutomatic LevelingLayer Thickness0.05-0.5mmMax Travel SpeedXY: Max. 300mm/sPrinting Nozzles2 Printing Nozzles Without Scratching, Able to Move up and DownExtruder TemperatureMax. 500°C/932°FPlatform TemperatureMax. 00°C/194°FFilament Box2 Spools, overall sealed design with molecular sieve dehumidification, built-in temp. and hum. monitoring sensor.Input File Type.Stl/.Obj/.X3d/.3mfFilament Diameter1.75mmPosition ResolutionXY: 16µmSmart Monitor & ControlFilament Jam Warning/Filament Absence Warning/Power Failure Recovery/ Liquid Cooling System/Auto-Cleaning Nozzles/Over Heat ProtectionSafety CertificationFCC/SGS/CE ConnectivitySupported Materials*PEEK/PEEK-CF/PEEK-GF/PEKK/PC/PC Alloys/PA/-CF/ASA/ABS/HIPS/PETG/ PLA/PVA/Carbon Fiber-Filled/Glass Fiber-Filled/ESD-Safe, etc. | | |
|---|-------------------------|---|
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| Position ResolutionXY: 16μmZ: 1.6μmSmart Monitor & ControlFilament Jam Warning/Filament Absence Warning/Power Failure Recovery/ Liquid Cooling System/Auto-Cleaning Nozzles/Over Heat ProtectionSafety CertificationFCC/SGS/CEConnectivityWiFi/Ethernet/USBSupported Materials*PEEK/PEEK-CF/ PEEK-GF/PEKK/PC/PC Alloys/PA/PA-CF/ASA/ABS/HIPS/PETG/ | Input File Type | .Stl/.Obj/.X3d/.3mf |
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| Connectivity WiFi/Ethernet/USB Supported Materials* PEEK/PEEK-CF/ PEEK-GF/PEKK/PC/PC Alloys/PA/PA-CF/ASA/ABS/HIPS/PETG/ | Smart Monitor & Control | |
| Supported Materials* PEEK/PEEK-CF/ PEEK-GF/PEKK/PC/PC Alloys/PA/PA-CF/ASA/ABS/HIPS/PETG/ | Safety Certification | FCC/SGS/CE |
| | Connectivity | WiFi/Ethernet/USB |
| | Supported Materials* | • • • • • • • • • • • • • |

*results of part printing may vary depending on material and/or design and size of the printed part

FUNMAT HT

Entry Level Desktop Industrial 3D Printer



<u> Advanced Thermal Design</u>

Heated Chamber Up to 90°C (194°F), Nozzle Temperature up to 450°C (842°F)

🗄 🛱 Smarter Design

Automatic Leveling, Filament Absence Warning



Ability to Print PEEK/PEKK/PC/PA/PA-CF/ABS/ASA and other Functional Materials



Technical Parameters

| Model | FUNMAT HT |
|-------------------------------------|--|
| Printing Technology | Fused Filament Fabrication (FFF) |
| Machine Size | 543×501×663mm (21.4×19.7×26.1in) |
| Build Volume | 260×260×260mm (10.2×10.2×10.2in) |
| Build Platform | PI Sheet Heating + Ceramic Glass |
| Leveling | Automatic Leveling |
| Layer Thickness | 0.05-0.3mm |
| Max Travel Speed | Max. 300mm/s |
| Extruder Temperature | Max. 450°C/842°F |
| Platform Temperature | Max. 160°C/320°F |
| Chamber Temperature | Max. 90°C/194°F |
| Input File Type | .Stl/.Obj |
| Filament Diameter | 1.75mm |
| Position Resolution | XY: 12.25μm Z: 1.25μm |
| Motor Drive | High Performance Independent Drivers |
| Safety Certification | FCC/SGS/CE |
| Supported Materials* | PEEK/PEEK-CF/ PEEK-GF/PEKK/PC/PC Alloys/PA/PA-CF/ASA/ABS/HIPS/TPU/ |
| | PETG/PLA/Carbon Fiber-Filled/Glass Fiber-Filled/ESD-Safe, etc. |
| *rocults of part printing many year | |

*results of part printing may vary depending on material and/or design and size of the printed part





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